

[54] **POLYESTER PRIMER FOR ADHESIVELY BONDED SUBSTRATES**

[76] Inventor: **Frederick D. Petke**, 1426 Watauga St., Kingsport, Tenn. 37664

[21] Appl. No.: **390,492**

[22] Filed: **Jun. 21, 1982**

Related U.S. Application Data

[63] Continuation-in-part of Ser. No. 172,914, Jul. 28, 1980, abandoned.

[51] Int. Cl.³ **C08F 265/04; C08L 67/02; C08F 267/00**

[52] U.S. Cl. **524/605; 525/305; 525/309; 427/412.1; 427/412.5; 427/412.4; 428/412; 428/421; 428/480; 428/481; 428/507; 428/537**

[57] **ABSTRACT**

Disclosed are primer compositions for enhancing the adhesion of hot-melt adhesives to substrates comprising a copolyester of at least 50 mole percent terephthalic acid, about 10-90 mole percent 1,4-butanediol or 1,6-hexanediol, and a solvating amount of a volatile solvent, the copolyester having an I.V. of about 0.3-1.5 dl/g and a melting point of about 100°-200° C.

13 Claims, No Sheets Drawing,

9 Pages-Specification

The file of this unexamined application may be inspected and copies thereof may be purchased (849 O.G. 1221, Apr. 9, 1968).